

ABSTRACT
PHOTOSENSITIVE SILICONE RESIN COMPOSITION

5 Provided is a resin composition which gives a cured
product of a photocurable resin having excellent crack
resistance even when formed into a thick film, and
capable of maintaining a low coefficient of linear
thermal expansion, low thermal weight loss, and a low
cure shrinkage. This photosensitive silicone resin
composition comprises (A) a silica particle-containing
10 condensation reaction product and (B) a
photopolymerization initiator, and is characterized in
that the silica particle- containing condensation
reaction product (A) is a condensation reaction product
of a polysiloxane compound (a) comprising a hydrolytic
15 condensation product of one or more silane compounds
represented by the following general formula (1):
 $R_{n1}^1SiX_{4-n1}^1$ (wherein R^1 , $n1$ and X^1 are defined in the
claims) and/or the silane compound, and silica particles
(b), and has a terminal structure Si-O-Y (wherein Y is
20 defined in the claims) which satisfies the following
formula (2): $0 < [Si-O-SiR_3^3]/([Si-O-R^2] + [Si-O-SiR_3^3]) \leq$
1 (wherein, R^2 and R^3 are defined in the claims), and has
a photopolymerizable functional group.

(No figure to accompany abstract)